LNP™ STAT-KON™ COMPOUND EJ000CXP

DESCRIPTION

LNP STAT-KON EJ000CXP is a static dissipative compound based on Polyetherimide (PEI) resin containing carbon nanotubes. Added features of this grade include: LNP Clean Compounding Technology, Dimensional Stability. This material has a fit in broad range of markets including the semiconductor industry.

GENERAL INFORMATION	
Features	Electrically Conductive, Low ionics/Outgassing/Liquid particle count, Dimensional stability, No PFAS intentionally added
Fillers	Carbon nanotube
Polymer Types	Polyetherimide (PEI)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Electronic Components
Industrial	Electrical, Material Handling

TYPICAL PROPERTY VALUES

Revision 20260326

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL [1]			
Tensile Stress, brk, Type I, 50 mm/min	105	MPa	ASTM D638
Tensile Strain, brk, Type I, 50 mm/min	4.5	%	ASTM D638
Tensile Modulus, 50 mm/min	3000	MPa	ASTM D638
Flexural Strength, 1.3 mm/min, 50 mm span	170	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	3500	MPa	ASTM D790
Tensile Stress, break, 50 mm/min	110	MPa	ISO 527
Tensile Strain, break, 50 mm/min	5	%	ISO 527
Tensile Modulus, 1 mm/min	3970	MPa	ISO 527
Flexural Strength, 2 mm/min	170	MPa	ISO 178
Flexural Modulus, 2 mm/min	3590	MPa	ISO 178
IMPACT [1]			
Izod Impact, notched, 23°C	45	J/m	ASTM D256
Izod Impact, unnotched, 23°C	NB	J/m	ASTM D4812
Izod Impact, notched 80*10*3 +23°C	6	kJ/m²	ISO 180/1A
Izod Impact, unnotched 80*10*3 +23°C	58	kJ/m²	ISO 180/1U
THERMAL [1]			
HDT, 0.45 MPa, 3.2 mm, unannealed	210	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	200	°C	ASTM D648
PHYSICAL [1]			
Specific Gravity	1.29	-	ASTM D792
Melt Volume Rate			
337°C/6.7 kg	6.1	cm³/10 min	ISO 1133

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PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Mold Shrinkage, flow [2]	0.5 – 0.7	%	SABIC method
Mold Shrinkage, xflow [2]	0.5 – 0.7	%	SABIC method
ELECTRICAL [1]			
Surface Resistivity	1.E+04 – 1.E+07	Ω	ASTM D257
INJECTION MOLDING [3]			
Drying Temperature	150	°C	
Drying Time	4 – 6	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	340 – 400	°C	
Nozzle Temperature	380 – 400	°C	
Front - Zone 3 Temperature	360 – 400	°C	
Middle - Zone 2 Temperature	350 – 390	°C	
Rear - Zone 1 Temperature	340 – 380	°C	
Mold Temperature	140 – 180	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	1.5 – 2	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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